

## Electronic Acknowledgement Receipt

<b>EFS ID:</b>	3923943
<b>Application Number:</b>	10595303
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	7114
<b>Title of Invention:</b>	Method and Device For Secure, Insulated and Electrically Conductive Assembling Of Treated Semiconductor Wafers
<b>First Named Inventor/Applicant Name:</b>	Roy Knechtel
<b>Customer Number:</b>	21967
<b>Filer:</b>	Jeff Vockrodt/Marcus Cunningham
<b>Filer Authorized By:</b>	Jeff Vockrodt
<b>Attorney Docket Number:</b>	60291.000048
<b>Receipt Date:</b>	11-SEP-2008
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<b>Application Type:</b>	U.S. National Stage under 35 USC 371

### Payment information:

Submitted with Payment	no
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### File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1		IDS.PDF	179201	yes	4
			b13388460623f1c166dcd925be3ea4ec192866ca		

	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Information Disclosure Statement Letter		1	2	
	Information Disclosure Statement (IDS) Filed (SB/08)		3	4	
Warnings:					
Information:					
2	Foreign Reference	GBpatapp.PDF	432339	no	16
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Warnings:					
Information:					
3	Foreign Reference	EURpatapp.PDF	357838	no	7
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Warnings:					
Information:					
4	Foreign Reference	DE19616014.PDF	628903	no	7
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Information:					
5	Foreign Reference	DE10141753.PDF	505480	no	5
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Warnings:					
Information:					
6	Foreign Reference	DE4006108.PDF	528227	no	7
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Warnings:					
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7	Foreign Reference	DE3837300.PDF	461242	no	5
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Warnings:					
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8	NPL Documents	ISR.PDF	112208	no	3
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9	NPL Documents	Jin.PDF	383500	no	6
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10	NPL Documents	Kadar.PDF	1242359	no	16
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Information:					
11	Fee Worksheet (PTO-06)	fee-info.pdf	30403	no	2
			1482a986abdaf5f6bf02ee48f07021568e045376		
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Information:					
Total Files Size (in bytes):			4861700		
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